

AMENDMENT

U.S. APPLN. NO.: 09/661,057

REMARKS

Review and reconsideration on the merits are respectfully.

Applicants have amended claim 3 in accordance with a preferred embodiment of the invention. In particular, the resin substrate is now defined as an epoxy resin substrate having been formed from a liquid epoxy resin and a solid epoxy resin. Support for this amendment can be found at, e.g., page 5, first full paragraph. In that location, the specification indicates that strength and heat resistance can be improved when a liquid epoxy resin is used in combination with a solid epoxy resin.

Applicants respectfully submit that none of the art of record discloses or suggests the subject matter of amended claim 3, for the reason of record and because the art of record, such as the primary reference to Hinata, fails to disclose or suggest a resin substrate as presently claimed. The Examiner previously had argued that Hinata discloses and shows a liquid crystal cell substrate comprising a polycarbonate film supporting substrate (9), which was argued to correspond to Applicant's resin substrate. Moreover, when a substrate obtained by flow-casting is employed, as in the present invention, smoothness of the substrate surface is good, in addition to an excellent mass-production property.

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For the foregoing reasons, allowance of the pending claims is respectfully requested.

Entry and consideration of this Amendment are respectfully requested.

Respectfully submitted,



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